



**PCN#20140917000
TNR Device orientation change for LMP92018SQ Devices
Information Only**

Date: 9/17/2014
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140917000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMP92018SQ/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140917000				PCN Date:	09/18/2014
Title:	TNR Device orientation change for LMP92018SQ Devices					
Customer Contact:	PCN Manager	Phone:	+1(214) 480-6037		Dept:	Quality Services
Change Type:						
<input type="checkbox"/> Assembly Site	<input type="checkbox"/>	Assembly Process		<input type="checkbox"/>	Assembly Materials	
<input type="checkbox"/> Design	<input checked="" type="checkbox"/>	Datasheet		<input type="checkbox"/>	Mechanical Specification	
<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling		<input type="checkbox"/>	Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material		<input type="checkbox"/>	Wafer Bump Process	
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials		<input type="checkbox"/>	Wafer Fab Process	
	<input type="checkbox"/>	Part number change				

PCN Details

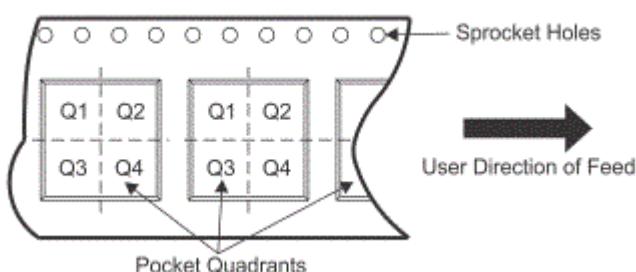
Description of Change:

The LMP92018SQ device orientation in TNR will be changed so that it will be will be consistent with JEDEC and EAI481-D standards. The device orientation will be changed from Quadrant 1 to Quadrant 2:

Device Table in Datasheet													
From	*All dimensions are nominal												
	Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	LMP92018SQ/NOPB	WQFN	NJK	36	1000	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q1
	LMP92018SQE/NOPB	WQFN	NJK	36	250	178.0	16.4	6.3	6.3	1.5	12.0	16.0	Q1
TO	*All dimensions are nominal												
	Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	LMP92018SQ/NOPB	WQFN	NJK	36	1000	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q2
	LMP92018SQE/NOPB	WQFN	NJK	36	250	178.0	16.4	6.3	6.3	1.5	12.0	16.0	Q2
	LMP92018SQX/NOPB	WQFN	NJK	36	2500	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q2

Reference TNR Quadrant Guide:

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Reason for Change:
To be consistent with JEDEC and EAI481-D standards.
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):
None
Changes to product identification resulting from this PCN:
None
Product Affected:
LMP92018SQ/NOPB LMP92018SQE/NOPB LMP92018SQX/NOPB

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com